



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

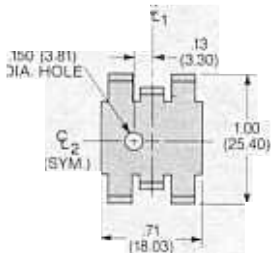
Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

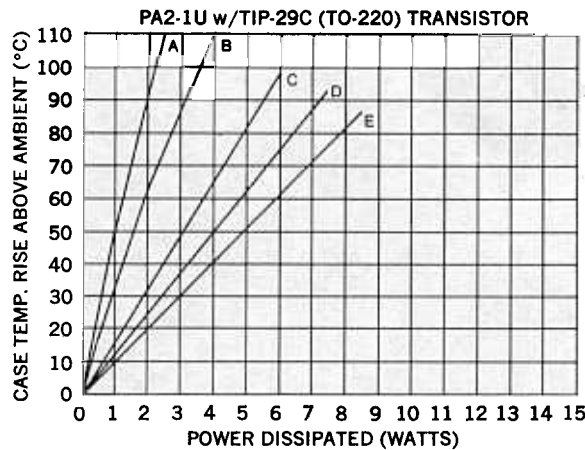
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PA2 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

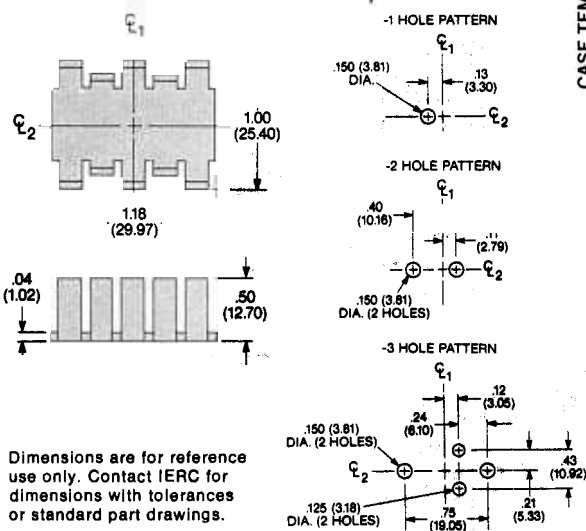
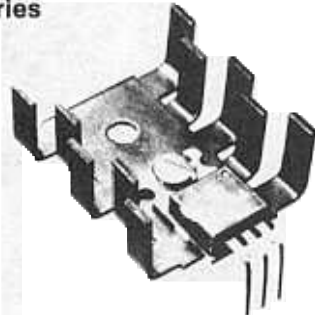
- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
- Derate 0.6 °C/watt for Insulube® part in natural convection only.

Ordering Information

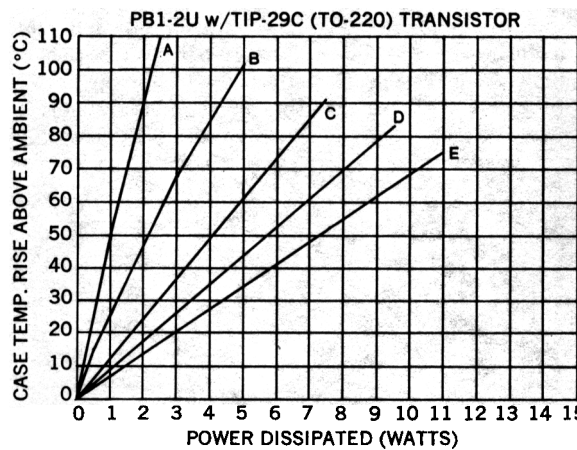
IERC PART NO.				Semiconductor Accommodated	Max. Weight (Grams)
Unplated	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448		
PA2U	PA2CB	PA2B	PA2	Undrilled TO-126, TO-127, TO-220	1.5
PA2-1U	PA2-1CB	PA2-1B	PA2-1		

Note: See page iv for other finishes.

PB1 Series



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.



DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

- Thermal Resistance Case to Sink is 0.9-1.1 °C/W w/Joint Compound.
- Uprate 2.4 °C/watt for black part in natural convection only.
- Derate 0.6 °C/watt for Insulube® part in natural convection only.

Ordering Information

IERC PART NO.				Semiconductor Accommodated	Max. Weight (Grams)
Unplated	Com'l. Black Anodize	Mil. Black Anodize	Insulube® 448		
PB1U	PB1CB	PB1B	PB1	Undrilled One TO-126, TO-127 or TO-220	3.0
PB1-1U	PB1-1CB	PB1-1B	PB1-1		
PB1-2U	PB1-2CB	PB1-2B	PB1-2	One or two TO-126, TO-127 or TO-220	3.0
PB1-3U	PB1-3CB	PB1-3B	PB1-3		

Note: See page iv for other finishes.